

Atomic Layer Deposition

What Is ALD ?

Subset of
Chemical
Vapor
Deposition
(CVD)



Atomic Layer Deposition

CVD

*Precursor gases injected
simultaneously
These react in gas phase to
produce film growth*

ALD

*Precursors gas injected
sequentially producing
surface only film growth*

ALD exposes surfaces with pulsed chemical vapours called precursors

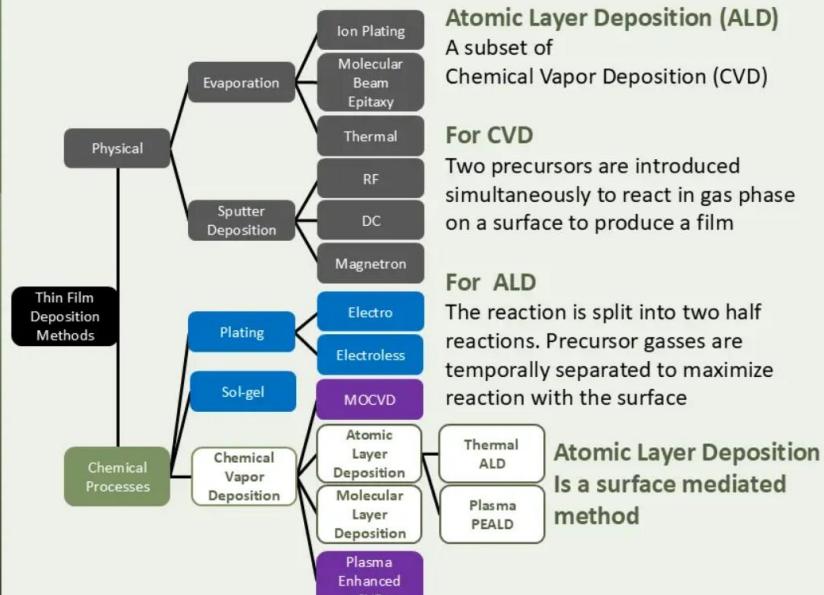
ALD exposes a surface sequentially with pulsed chemical vapours separated by a nitrogen purge. A first precursor forms one monolayer of coating by reacting with the substrate surface (usually with OH groups terminating a surface). The next precursor reacts with the surface of the previously formed monolayer and forms another monolayer. Usually two different precursors are used, resulting in binary coating materials (like Al₂O₃), although elemental coatings (pure metals etc.) and much more complex compositions are also possible

The number of monolayers of the coating (thickness) can be determined simply by setting the number of sequential pulses. The vapours do not condense on the surface, because the excess vapour is evacuated between the precursor pulses using a nitrogen purge. This means that the coating after each pulse is self-limiting to one monolayer. This allows complex shapes to be coated with atomic precision (the coating thickness inside a porous material will be the same as on its surface!). Due to this and many more remarkable features, ALD is becoming increasingly popular for more and more applications

What is ALD?

Thin film deposition methods

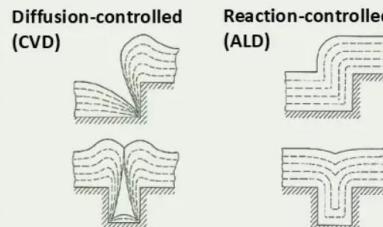
Thin film deposition methods



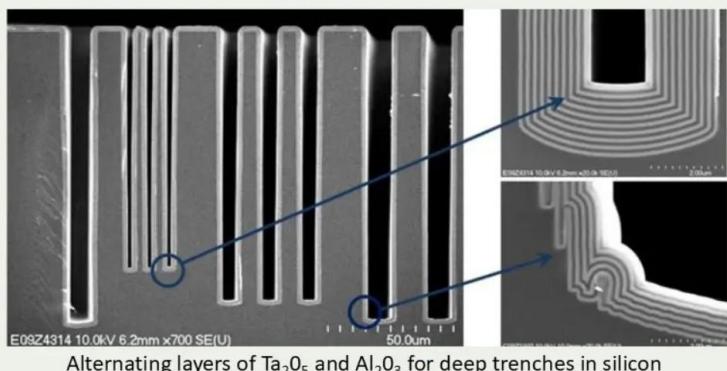
The ALD advantage

Conformal deposition for complex geometry

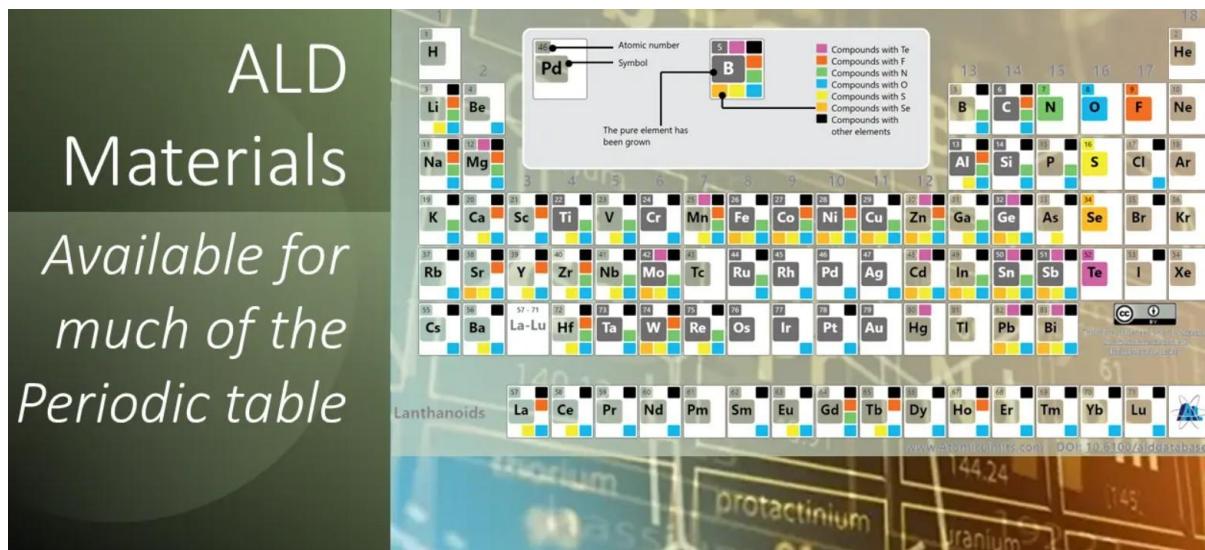
ALD is a reaction-controlled method



Produces conformal Pin-hole free deposition on complex geometry with large L/D ratio



The inherent strength of ALD technology



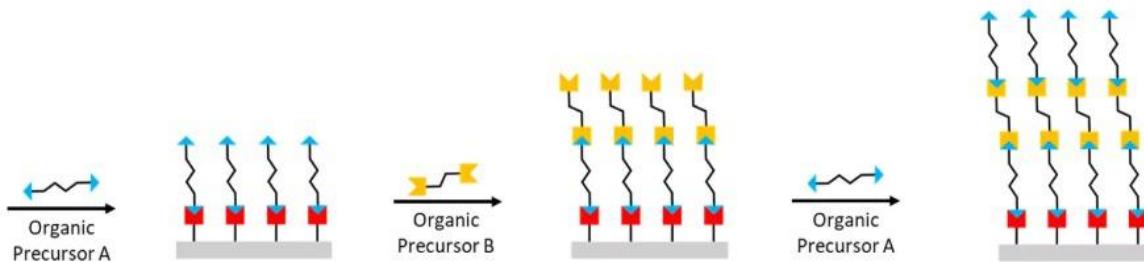
Is the ability to utilize much of the materials available on the periodic table as shown above. In addition, conformity and the ability to adapt to various substrates, shapes and high aspect ratio structures producing uniform, pinhole free single material and Nano-laminate coatings has created broad interest in many fields.

Molecular Layer Deposition (MLD)

MLD is a gas phase deposition technology

Extending the Toolbox of Gas Phase Deposited Materials with GEMStar XT-D

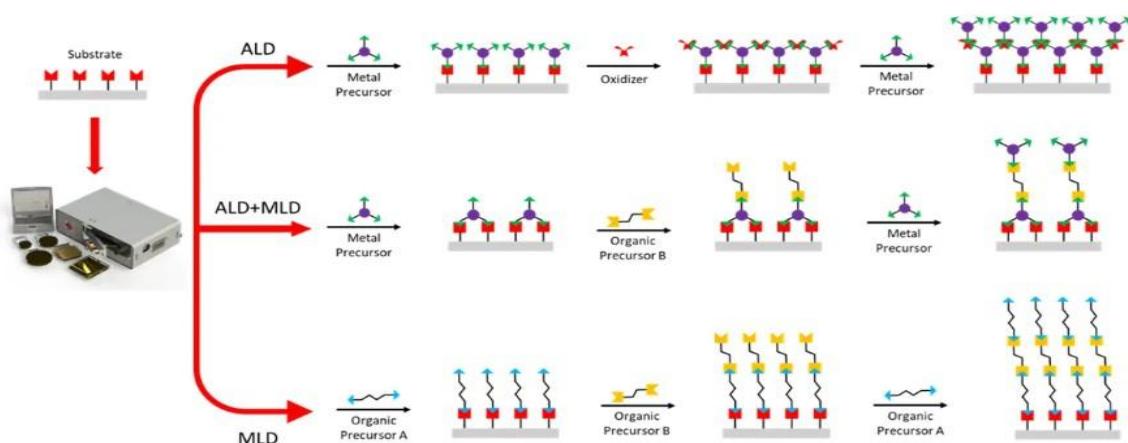
Molecular Layer (MLD) is a gas phase deposition technique. It can be used to deposit thin conformal organic polymers such as polyamides, polyimides, and polyesters to name a few. Similar to ALD, MLD separates the reaction of co-reacting chemicals into two surface- mediated half reactions separated by a purge step.



With a unique dual manifold design

Patent pending gas distribution

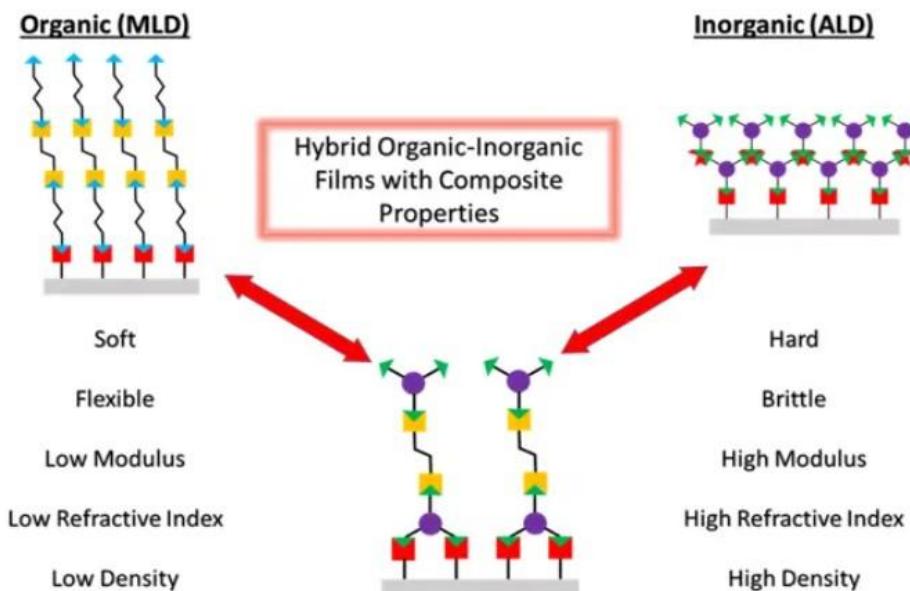
Arradiance's GEMStar XT-D is the ideal tool for depositing MLD and ALD films. By separating co-reacting precursors within two individually heated manifolds, deposition and film growth only occur within the chamber and not within the manifold lines. This key feature separates the GEMStar- XT-D from other commercially available ALD tools and is the only Benchtop tool capable of safely depositing ALD and MLD films. Furthermore, the compact and small footprint of the GEMStar XT-D takes up minimal lab space and can easily be integrated to any Glovebox making it an ideal tool for air sensitive research.



Some organic precursors can react with inorganic precursors

Defining a new class of hybrid organic-inorganic thin films. These hybrid materials have properties that range between pure organic and inorganic films, allowing for control over density, refractive index, elastic modulus, and hardness

This enables developing films with precisely tuned mechanical, optical, chemical bio-chemical, and electrical properties, further extending the range of materials that can be deposited. Given these unique tuneable properties, ALD and MLD have found application in a number of difference fields including energy storage, fuel cells, photovoltaics, biotechnology and semiconductors to name a few.



MLD	Organic Precursor A	Organic Precursor B	ALD+ MLD	Metal Precursor	Organic Precursor B
Polyimide	 Pyromellitic dianhydride	$\text{H}_2\text{N}-\text{CH}_2-\text{NH}_2$ Ethylene Diamine	Alucone	$\text{CH}_3-\text{Al}(\text{CH}_3)_2$ Trimethylaluminum	$\text{HO}-\text{CH}_2-\text{OH}$ Ethylene Glycol
Polyurea	 P-Phenylene diisocyanate	$\text{H}_2\text{N}-\text{CH}_2-\text{NH}_2$ Ethylene Diamine	Titanicone	$\text{Cl}-\text{Ti}(\text{Cl})_2-\text{Cl}$ Titanium Chloride	$\text{HO}-\text{CH}_2-\text{OH}$ Glycerol
Polyester	 Terephthaloyl chloride	$\text{HO}-\text{CH}_2-\text{OH}$ Ethylene Glycol	LiPON	$\text{CH}_3-\text{CH}(\text{CH}_3)-\text{O}-\text{Li}$ Lithium Tert-Butoxide	$\text{H}_3\text{C}-\text{O}-\text{P}(\text{O})(\text{NH}_2)-\text{O}-\text{CH}_3$ Diethyl Phosphoramide